In the Claims

1. (Currently Amended) An antistatic film with a surface resistivity of no greater than [[10^{13}]] 10^8 Ω/□, comprising a metal oxide and conductive ultrafine particle mixed layer formed on the surface of a film, wherein the film is a polyimide film having a thickness of 7.5-125 μm, and the metal oxide and conductive ultrafine particle mixed layer comprises a metal of the metal oxide and conductive ultrafine particles in a weight ratio (metal/conductive ultrafine particles) of 0.01-0.1, and the metal oxide and conductive ultrafine particle mixed layer has a thickness of 0.05-0.15 μm.

2. – 3. (Cancelled)

4. (Previously Presented) The antistatic film according to claim 3, wherein the polyimide film is obtained from a tetracarboxylic acid component and a diamine component.

5. (Previously Presented) The antistatic film according to claim 4, wherein the tetracarboxylic acid component is 3,3',4,4'-biphenyltetracarboxylic dianhydride.

6. (Previously Presented) The antistatic film according to claim 1, wherein the metal oxide is an aluminum oxide.

7. (Previously Presented) The antistatic film according to claim 1, wherein the conductive ultrafine particles have a mean particle size of no greater than 0.1 μm.

8. (Previously Presented) The antistatic film according to claim 1, wherein the conductive ultrafine particles are ITO ultrafine particles.

9. (Previously Presented) The antistatic film according to claim 1, wherein the mixed layer is formed by a coating method.

10. (Previously Presented) A process for manufacture of an antistatic film according to claim 1, comprising:

coating the surface of a self-supporting film, obtained by casting and drying a solution of a film-forming heat-resistant resin precursor, with a mixture obtained by uniformly combining a metal compound which converts to a metal oxide upon heating, conductive ultrafine particles and a solvent,

heating the mixture to dryness,

removing the solvent, and

cyclizing the heat-resistant resin precursor.

11. (Previously Presented) The process according to claim 10, wherein the metal compound which converts to a metal oxide upon heating is an organic aluminum compound.

12. (Currently Amended) A process for manufacture of an antistatic film comprising:

coating a surface of a self-supporting film, obtained from a polyimide precursor solution, with a mixture comprising a metal compound which converts to a metal oxide upon heating, conductive ultrafine particles and a solvent, drying the mixture to obtain a dry film with a metal compound and conductive ultrafine particle mixed layer, and heating the dry film at a temperature of 420°C or above to complete imide cyclization to thereby form on the film surface a metal oxide and conductive ultrafine particle mixed layer having a surface resistance value of no greater than [[10^{13}]] 10^{8} Ω/□ and the film is a polyimide film having a thickness of 7.5-125 μm, and the metal oxide and conductive ultrafine particle mixed layer comprises a metal of the metal oxide and conductive ultrafine particles in a weight ratio (metal/conductive ultrafine particles) of 0.01-0.1, and the metal oxide and conductive ultrafine particle mixed layer has a thickness of 0.05-0.15 μm.

13. (Currently Amended) An antistatic film with a surface resistivity of no greater than [[10^{13}]] 10^{8} Ω/□, comprising a metal oxide and conductive ultrafine particle mixed layer formed on the surface of a film, wherein the conductive ultrafine particles are firmly held in the film by the metal oxide, thereby allowing the surface resistance value to be kept within less than 10-fold compared to the initial value, even if a release effect is conferred by an adhesive tape at a pull rate of 60 m/min and wherein the film is a polyimide film having a thickness of 7.5-125 μm, and the metal oxide and conductive ultrafine particle mixed layer comprises a metal of the metal oxide and conductive ultrafine particles in a weight ratio (metal/conductive ultrafine particles) of 0.01-0.1, and the metal oxide and conductive ultrafine particle mixed layer has a thickness of 0.05-0.15 μm.

14.-15. (Cancelled)

16. (Previously Presented) The antistatic film according to claim 13, wherein the polyimide film is obtained from a tetracarboxylic acid component and a diamine component.

17. (Previously Presented) The antistatic film according to claim 13, wherein the tetracarboxylic acid component is 3,3',4,4'-biphenyltetracarboxylic dianhydride.

18. (Previously Presented) The antistatic film according to claim 13, wherein the metal oxide is an aluminum oxide.

19. (Previously Presented) The antistatic film according to claim 13, wherein the conductive ultrafine particles have a mean particle size of no greater than 0.1 μm.

20. (Previously Presented) The antistatic film according to claim 13, wherein the conductive ultrafine particles are ITO ultrafine particles.

21. (Previously Presented) The antistatic film according to claim 13, wherein the mixed layer is formed by a coating method.

22. (New) The antistatic film according to claim1, having a surface resistivity of 10^4 -10^8 Ω/□.

23. (New) The process according to claim12, where the film has a surface resistivity of 10^4 -10^8 Ω/□.

24. (New) The antistatic film according to claim13, having a surface resistivity of 10^4 -10^8 Ω/□.